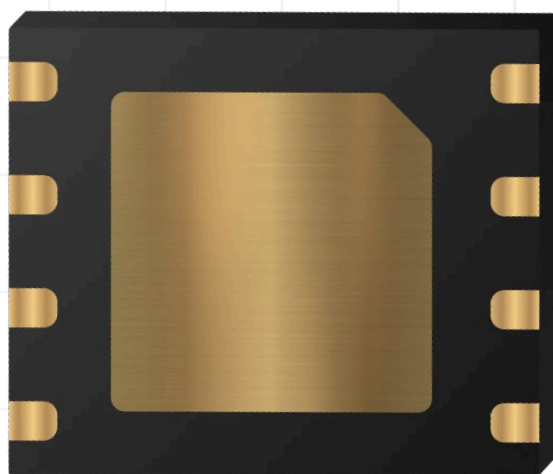


Embedded format



Hyper eUICC SIM

Hyper eUICC SIM – Embedded format

Product overview

A secure, device-agnostic IoT embedded SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs use an eUICC OS to remotely update coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

Primary part number

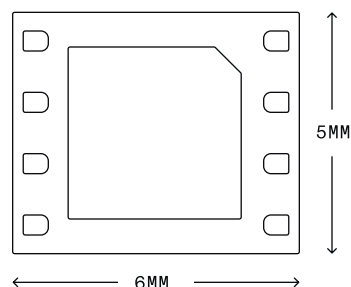
G3-F-DFN8

Network availability

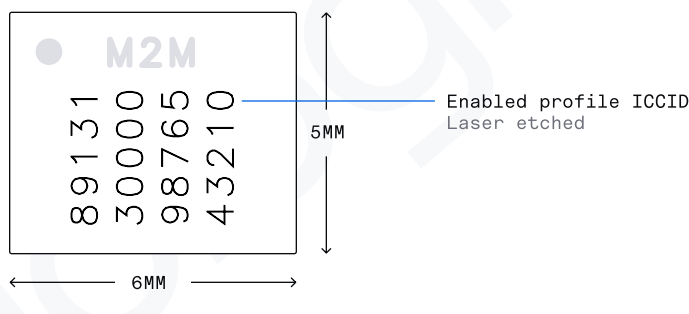
Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

Mechanical specifications

Bottom view

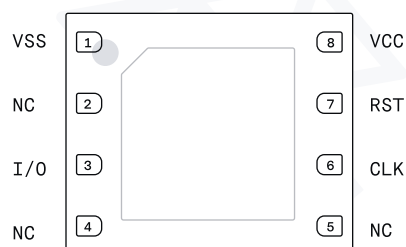


Top view



Physical characteristics

Top view



Pin definitions

1	VSS	Voltage Source Supply
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

Size

MFF2 (DFN8)	Embedded SIM	6 × 5 × 0.82 mm
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Hardware features

Chip type

Supplier	Infineon
Chip Code	SLM17ECB800B

Electrical

Operating Voltage	1.62V to 5.5V
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Hardware characteristics

Grade	Industrial
Operational Temperature	−40°C to +105°C
Data Retention	20 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	330 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 – Smart Cards; UICC–Terminal interface; Physical and logical characteristics
ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

Compliance

Chip	 Common Criteria	EAL 4+ PP-0084 (chipset) Certificate: BSI-DSZ-CC-1126-V2-2021
		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
OS	 TRUSTED CONNECTIVITY ALLIANCE	eUICC Profile Package Interoperable Format Technical Specification v2.3.1
		Card Specification Version 2.3.1 Card Specification Amendments A, B, D & E
Software		Java Card 3 Platform, Classic Edition version 3.0.5
		Release 16
Remote SIM provisioning		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
Supplier's Declaration of Conformity		Manufactured according to the following standards: • RoHS 2015/863/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 14001

SIM features

Profiles and fallback

Available user memory	414,384 B
Maximum profiles	10
Applet version	v1 Fallback applet
Default fallback mode	Return to previous, no recovery

Part numbers

Active part numbers	Past part numbers
G3-F-DFN8	G3-DFN8
G3-G2-DFN8	G3-G2-F-DFN8
G2-F-DFN8	GL2-AFB-MFF2
US2+-G2-F-DFN8	GL2-USA2+-AFB-MFF2
US2M-G2-F-DFN8	GL2-USA2M-AFB-MFF2
CA1-G2-F-DFN8	—

Multipack labeling	Part numbers
Single SIM	G3-F-DFN8
250-pack	G3-F-DFN8-250
250-pack	G3-F-DFN8-2500